

The main IC Junction temperature must be limited to 125°C. Thermal resistance from the junction to the case top is 7.6°C/W. Thermal resistance from the junction to the case bottom is 10.0 °C/W.

Heat sinking may be required in some applications with high load and inadequate air flow. This may be accomplished by using a ~0.3" x 0.3" gap pad and heat sink in the area indicated, or by applying a heat sink to the top center of the main IC.

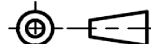
5X Ethernet Ports		
Mating Molex Connector: 0510210800		
1	TP3 P	RJ45 P7
2	TP3 N	RJ45 P8
3	TP2 P	RJ45 P5
4	TP2 N	RJ45 P4
5	TP1 P	RJ45 P3
6	TP1 N	RJ45 P6
7	TP0 P	RJ45 P1
8	TP0 N	RJ45 P2

Power		
Mating Molex Connector: 0510210400		
1	GND	
2	GND	
3	VIN	4-42 VDC
4	VIN	

Ports In Use	Power Usage (Watts)
0	0.5
1	1.2
2	1.8
3	2.4
4	3
5	3.8

Size: 2.1 in³
Weight: 25g

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UNLESS OTHERWISE SPECIFIED:		NAME	DATE	Gadgetsmyth LLC 1134 South 1680 West Orem UT, 84058	
DIMENSIONS ARE IN INCHES TOLERANCES: FRACTIONAL ± 1/8 DECIMAL .XX ± 0.01 .XXX ± 0.005 ANGLES ± 1° DO NOT SCALE DRAWING	DRAWN	LM	7/5/2018		
	CHECKED	JH	7/5/2018		
MATERIAL				TITLE: GigEthos Lite Ethernet Switch Drawing	
COMMENTS:					
THIRD ANGLE PROJECTION				SIZE	ACS-ETH1-10-ICD RevC
				SCALE: 3:2	SHEET 1 OF 1